

BIOGRAPHY

Advanced Packaging Summit 2026



Name: Sandeep Sane

Title/ Position: Vice President

Company: Lightmatter

Sandeep Sane is Vice President at Lightmatter, where he drives the strategy and execution of advanced packaging technologies for the company's cutting-edge Passage and LASER product lines. With over two decades of industry leadership, Sandeep brings deep expertise in semiconductor packaging, system architecture, and high-performance computing platforms.

Prior to Lightmatter, he served as a Principal Engineer at Intel, where he played a pivotal role in the development of silicon-package co-design methodologies and led key innovations in manufacturing, reliability, and cost optimization. He is a co-inventor of Intel's industry-leading EMIB packaging technology, with more than 30 patents and a strong track record of publications and leadership in the field.

Sandeep began his career at IBM's Microelectronics Division and holds a Ph.D. and M.S. from Caltech, along with a B.S. from IIT Bombay. He is an active member of ASME and a recognized voice in the semiconductor packaging community.